

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	(nano\$1probe (nano adj probe)) with ((substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) with silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 14:36
L2	2	I1 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 14:35
L3	42	(nano\$1probe (nano adj probe)) with (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 15:23
L4	35	I3 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 15:23
L5	23	I4 and silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 14:36
L7	3	I5 and (project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 14:37
L16	76	(nano\$1probe (nano adj probe)) same (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 15:23

L17	66	I16 and @ad<"20030922"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 15:23
L20	7	I17 and ((project\$5 protrud\$5 extend\$5) near2 (portion part member moiety parcel piece section segment))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 15:29
L21	3	I20 and (conduct\$5 near2 (wir\$3 cord\$3 cabl\$3 line link channel connect\$5 lead\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/23 15:27